

# CFP2

Amphenol ICC's CFP2 series offers a 104 position, 0.6mm pitch connector designed to be compatible with 100Gb/s Form Factor Pluggable (CFP) Multi-Source Agreement for Ethernet and other applications. It is used in multi-hundred Gb/s systems and is comprised of insert molding assemblies for top contacts and press-fit cage assemblies. Rated for 25Gb/s per channel with resonance dampening for improved signal integrity, CFP2 has up to 60% lower power consumption versus CFP. An optional riding heat sink ensures proper thermal dissipation. Compatible with IEEE and ITU-T applications, the CFP2 footprint is compliant with other industry suppliers.



# **TECHNICAL INFORMATION**

#### **MATERIAL**

- Housing: Black color, Glass reinforced, Lead Free Solder Reflow Process Compatible Thermo Plastic
- Contacts Base Material: Phosphor Bronze
- Plating Solder Tails: Matte tin
- Plating Mating Area: Gold
- Resonance Dampening Feature: Conductive Polymer

#### **MECHANICAL PERFORMANCE**

- Durability: 200 mating cycles
- Mating Force: 80 N max.
- Contact Normal Force: 40 grams
- PCB Thickness (Cage): 3.00 mm (0.118 in.)
- Unmating Force (Cage): 50 N
- Insertion Force to PCB (Cage): 2 port 2000N max.

#### **ELECTRICAL PERFORMANCE**

- Operating Voltage: 3.3 V DC per contact
- Operating Current (per power pin): 0.5A maximum (Class 4 or lower) / 1.25A maximum (Class 5 and 6)
  - Please contact the manufacturer for specific requirements over 0.5A per pin
- Operating Current (per signal pin): 0.5A maximum
- Differential Impendance:  $100\Omega + /- 10\Omega$

#### **ENVIRONMENTAL**

- Operating and (Storage) Temperature: -40°C to +85°C
- RoHS & Halogen-Free

#### **TOOLING INFORMATION**

• Configurations: 1X1, 1X2

## **TARGET MARKETS/APPLICATIONS**



Metro Area Networks

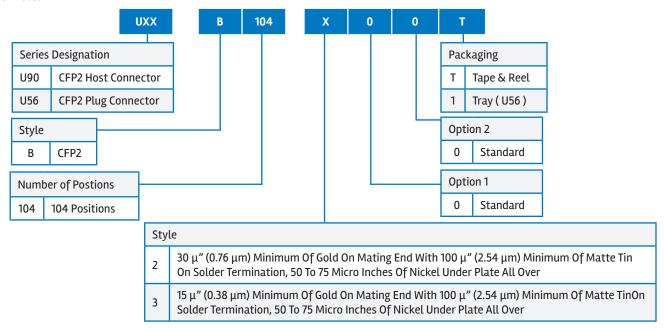


Carrier Networks and Data Centers Large Data Center Campus Connectivity

### CFP2

# **PART NUMBER SELECTOR**

#### **CFP2 Connector**



### CFP2 Cage

